CYW20737S



Bluetooth Low Energy System-in-Package (SiP) Module

The CYW20737S is a compact, highly integrated Bluetooth Low Energy (BLE) system-in-package (SiP) module. The CYW20737S SiP includes an embedded BLE antenna, 24 MHz clock, and 512 Kb EEPROM, so only a minimal set of external components is needed to create a standalone BLE device.

The CYW20737S is designed to accelerate time to market. The Bluetooth stack and several application profiles are built into the module, allowing customers to focus on their core applications. To further reduce application development time, the CYW20737S includes integrated software support, with one-click installation of the complete environment and a one-click compile/build/link/load cycle. All this, coupled with an ultrasmall form factor and support for a wide voltage range, makes the CYW20737S well suited for virtually any Bluetooth Smart application.

Cypress Part Numbering Scheme

Cypress is converting the acquired IoT part numbers from Broadcom to the Cypress part numbering scheme. Due to this conversion, there is no change in form, fit, or function as a result of offering the device with Cypress part number marking. The table provides Cypress ordering part number that matches an existing IoT part number.

Table 1. Mapping Table for Part Number between Broadcom and Cypress

Broadcom Part Number	Cypress Part Number
BCM20737S	CYW20737S
Features	Applications
ARM Cortex-M3 microcontroller unit (MCU)	Profiles supported in ROM:
■ Embedded 512 Kb EEPROM	■ Battery status
Broadcom Serial Control (BSC), SPI, and UART interface	Blood pressure monitor
■ FCC and CE compliant	■ Find me
RoHS compliant, certified lead- and halogen-free	Heart rate monitor
Moisture Sensitivity Level (MSL) 3 compliant	Proximity
■ 6.5 mm × 6.5 mm × 1.2 mm Land Grid Array (LGA) 48-pir	■ Thermometer
package	■ Weight scale
	■ Time
	Blood glucose monitor
	Support for RSA security library
	Support for LE Audio
	Support for pairing using NFC tags
	Additional profiles supported in RAM:
	Blood glucose monitor
	■ Temperature alarm
	■ Location
	Other custom profiles

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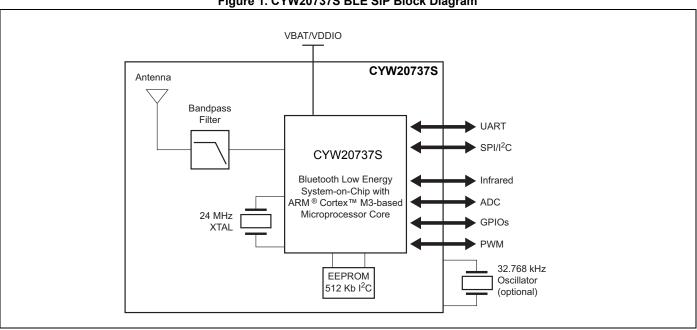


Figure 1. CYW20737S BLE SiP Block Diagram

IoT Resources

Cypress provides a wealth of data at http://www.cypress.com/internet-things-iot to help you to select the right IoT device for your design, and quickly and effectively integrate the device into your design. Cypress provides customer access to a wide range of information, including technical documentation, schematic diagrams, product bill of materials, PCB layout information, and software updates. Customers can acquire technical documentation and software from the Cypress Support Community website (http://community.cypress.com/).



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1. Functional Description

1.1 External Reset

External reset timing for the CYW20737S is illustrated in Figure 2.

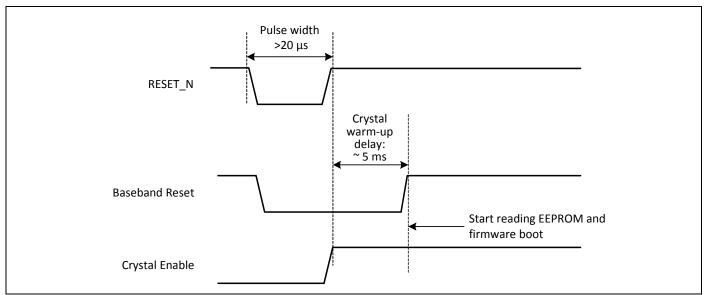


Figure 2. External Reset Timing

1.2 32.768 kHz Oscillator

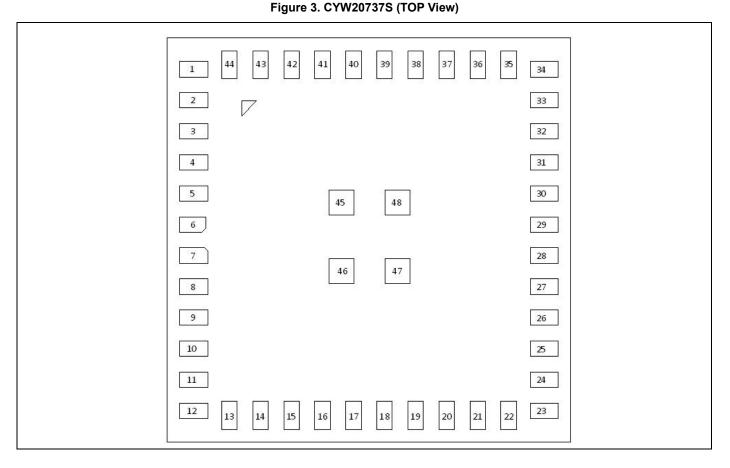
The CYW20737S includes a standard Pierce oscillator. The oscillator circuit includes a comparator with hysteresis on the output to create a single-ended digital output. The hysteresis eliminates chatter when the input is near the comparator threshold (~100 mV). The oscillator circuit can is designed for a 32 kHz or 32.768 kHz crystal oscillator, and can also be driven by an external clock input with a similar frequency. Characteristics for a 32 kHz oscillator are defined in Table 2.

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Output frequency	F _{oscout}	-	_	32.768	_	kHz
Frequency tolerance	F _{tol}	Crystal-dependent	-	100	_	ppm
Start-up time	T _{startup}	-	-	-	500	μs
Crystal drive level	P _{drv}	For crystal selection	0.5	-	-	μW
Crystal series resistance	R _{series}	For crystal selection	-	-	70	kΩ
Crystal shunt capacitance	C _{shunt}	For crystal selection	-	-	1.3	pF



2. Pin Map and Signal Descriptions

The CYW20737S pin map is shown in Figure 3.



The signal name, type, and description of each pin in the CYW20737S is listed in Table 3 on page 6. The symbols shown under I/O Type indicate pin directions (I/O = bidirectional, I = input, O = output) and the internal pull-up/pull-down characteristics (PU = weak internal pull-up resistor and PD = weak internal pull-down resistor), if any.



Table 3. Pin Descriptions

Pin	Name	I/O Type	Description
1	GPIO: P27 PWM1	I	Default direction: Input. After POR state: Input floating. Drain current: 16 mA Alternate function: MOSI (master and slave) for SPI_2
2	GND	GND	GND
3	VBAT	I	Battery supply input.
4	GND	GND	GND
5	GND	GND	GND
6	GND	GND	GND
7	GND	GND	GND
8	GND	GND	GND
9	GND	GND	GND
10	Reserved	_	Leave floating
11	GND	GND	GND
12	GND	GND	GND
13	GND	GND	GND
14	GND	GND	GND
15	GND	GND	GND
16	GND	GND	GND
17	GND	GND	GND
18	UART_RX	I	UART_RX. This pin is pulled low through an internal 10 k Ω resistor.
19	UART_TX	O, PU	UART_TX
20	GND	GND	GND
21	SCL	I/O, PU	SCL I/O, PU clock signal for an external I ² C device
22	SDA	I/O, PU	SDA I/O, PU data signal for an external I ² C device
23	GND	GND	GND
24	GND	GND	GND
25	GPIO: P1	I	Default direction: Input. After POR state: Input floating. This pin is tied to the WP pin of the embedded EEPROM. Requires an external 10K pull-up
26	ТМС	Ι	Test mode control. Pull this pin high to invoke test mode; leave it floating if not used. This pin is connected to GND through an internal 10 k Ω resistor.
27	RESET_N	I/O PU	Active-low system reset with open-drain output



Table 3. Pin Descriptions (Cont.)

Pin	Name	I/O Type	Description
			Default direction: Input. After POR state: Input floating. Alternate functions:
			■ A/D converter input
28	GPIO: P0	I	Peripheral UART TX (PUART_TX)
			MOSI (master and slave) for SPI_2
			■ IR_RX
			■ 60Hz_main
29	GND	GND	GND
30	GPIO: P3	1	Default direction: Input. After POR state: Input floating. Alternate functions:
50	0110.13	1	■ Peripheral UART CTS (PUART_CTS)
			SPI_CLK (master and slave) for SPI_2
			Default direction: Input. After POR state: Input floating. Alternate functions:
31	GPIO: P2	I	■ Peripheral UART RX (PUART_RX)
			■ SPI_CS (slave only) for SPI_2
			SPI_MOSI (master only) for SPI_2
			Default direction: Input. After POR state: Input floating. Alternate functions:
32	GPIO: P4	I	■ Peripheral UART RX (PUART_RX)
			MOSI (master and slave) for SPI_2.
			■ IR_TX
33	GPIO: P8	I	Default direction: Input. After POR state: Input floating. Alternate functions: A/D converter input.
			Default direction: Input. After POR state: Input floating. Alternate functions:
34	GPIO: P33		■ A/D converter input
54	0110.1.33		■ MOSI (slave only) for SPI_2
			Auxiliary clock output (ACLK1)
			Peripheral UART RX (PUART_RX)



Table 3. Pin Descriptions (Cont.)

Pin	Name	I/O Type	Description
			Default direction: Input. After POR state: Input floating. Alternate functions:
35	GPIO: P32	1	■ A/D converter input
00			■ SPI_CS (slave only) for SPI_2.
			 Auxiliary clock output (ACLK0)
			Peripheral UART TX (PUART_TX)
36	GPIO: P25		Default direction: Input. After POR state: Input floating. Alternate functions:
00	0110.120		MISO (master and slave) for SPI_2
			Peripheral UART RX (PUART_RX)
37	GPIO: P24		Default direction: Input. After POR state: Input floating. Alternate functions:
01	01101121		SPI_CLK (master and slave) for SPI_2
			Peripheral UART TX (PUART_TX)
38	NC	NC	No Connection (N/C).
	GPIO: P13 PWM3	I	Default Direction: Input After POR State: Input Floating Drain current: 16 mA Alternate function: A/D converter input
39	GPIO: P28		Default direction: Input. After POR state: Input floating. Drain current: 16 mA Alternate functions:
	PWM2	1	■ A/D converter input
			■ LED1
			■ IR_TX
	GPIO: P14 PWM2	I	Default direction: Input. After POR state: Input floating. Alternate function: A/D converter input
40			Default direction: Input. After POR state: Input floating. Alternate functions:
	GPIO: P38	I	■ A/D converter input
			MOSI (master and slave) for SPI_2
			■ IR_TX
			Default direction: Input. After POR state: Input floating. Alternate functions:
41	GPIO: P15	I	■ A/D converter input
			■ IR_RX
			■ 60 Hz_main



Table 3. Pin Descriptions (Cont.)

Pin	Name	I/O Type	Description
42	GPIO: P26 PWM0	I	Default direction: Input. After POR state: Input floating. Drain current: 16 mA Alternate function: SPI_CS (slave only) for SPI_2
43	GPIO: P12	I	Default direction: Input. After POR state: Input floating. Alternate functions: A/D converter input XTALO32K
	XTALO32K	0	Low-power oscillator (LPO) output. Alternate functions: P12 P26
44	GPIO: P11	I	Default direction: Input. After POR state: Input floating. Alternate functions: A/D converter input XTALI32K
	XTALI32K	I	Low-power oscillator (LPO) input. Alternate functions: P11 P27
45	GND	GND	GND
46	GND	GND	GND
47	GND	GND	GND
48	GND	GND	GND



3. Electrical Specifications

Absolute maximum ratings are defined in Table 4.

Table 4. Absolute Maximum Ratings

Parameter	Min.	Max.	Unit
Supply power	NA	3.63	V
Storage temperature	-40	125	°C
Voltage ripple	0	±2	%
Power supply (VBAT absolute maximum rating)	1.62	3.63	V

Power for the CYW20737S module is provided by the host through the power pins.

Table 5. Voltage

Symbol	Parameter	Min.	Тур.	Max.	Unit
VBAT	Battery voltage	1.62	-	3.63	V

Table 6. Current Consumption

Operating Mode	Condition	Nominal	Maximum	Unit
Receive	Receiver and baseband are both operating, 100%	24.0	28.0	mA
Transmit	Transmitter and baseband are both operating, 100%	24.0	28.0	mA
Sleep	Wake in < 5 ms	55.0	60.0	μA
Deep Sleep	Wake on interrupt	2.0	2.5	μA

Note: All measurements taken at 25°C

Based on the current measurements in Table 6 on page 10, CYW20737S peak power values are:

- RX: 101.6 mW
- TX: 101.6 mW
- Sleep mode: 217.8 µW
- Deep Sleep mode: 9.1 µW



4. RF Specifications

CYW20737S receiver specifications are defined in Table 7.

Table 7. Receiver Specifications

Parameter	Mode and Conditions	Min.	Тур.	Max.	Unit
Frequency range	_	2402	_	2480	MHz
RX sensitivity (standard)	Packets: 200 Payload: PRBS 9 Length: 37 Bytes Dirty Transmitter: off. PER: 30.8%	_	-94	-	dBm
Maximum input	_	-10	_	_	dBm

Note: All measurements taken at 3.0V (default voltage)

RF transmitter specifications are defined in Table 8.

Table 8. Transmitter Specifications

Parameter	Min.	Тур.	Max.	Unit
Transmitter	Ŀ			
Frequency range ^a	2402	-	2480	MHz
Output power adjustment range	-20	-	4	dBm
Output power	-	2	_	dBm
Output power variation	-	2.5	-	dB
LO Performance		•	•	
Initial carrier frequency tolerance	-	_	±150	kHz
Frequency Drift	Ŀ			
Frequency drift	_	_	±50	kHz
Drift rate	-	_	20	kHz/50 μs
Frequency Deviatio	on	•	•	
Average deviation in payload (sequence: 00001111)	225	-	275	kHz
Average deviation in payload (sequence: 10101010)	185	-	-	kHz
Channel spacing	-	2	-	MHz

a. This parameter is taken from the Bluetooth 4.0 specification.



5. ADC Specifications

CYW20737S ADC specifications are defined in Table 9.

Table 9. ADC Specifications

Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Number of input channels	-	_	-	9	_	-
Channel switching rate	f _{ch}	_	-	_	133.33	Kch/s
Input signal range	V _{inp}	_	0	-	3.63	V
Reference settling time	-	Charging refsel	7.5	-	-	μs
Input resistance	R _{inp}	Effective, single-ended	-	500	-	kΩ
Input capacitance	C _{inp}	_	-	-	5	pF
Conversion rate	F _c	-	5.859	_	187	kHz
Conversion time	T _c	-	5.35	_	170.7	μs
Resolution	R	_		16		Bits
Absolute voltage measurement error	_	Using on–chip ADC firmware driver	-	±2	-	%
Current	I	I _{avdd1p2} + I _{avdd3p3}	_	_	1	mA
Power	Р	-	_	1.5	_	mW
Leakage Current	I _{leakage}	T = 25°C	-	-	100	nA
Power-up time	T _{powerup}	_	-	-	200	μs
Integral nonlinearity	I _{NL}	In the guaranteed performance range	-1	-	1	LSB ^a
Differential nonlinearity	D _{NL}	In the guaranteed performance range	-1	-	1	LSB ^a

a. LSBs are expressed at the 10-bit level.



6. Timing and AC Characteristics

6.1 SPI Timing

SPI interface timing is illustrated in Figure 4 and Figure 5 and defined in Table 10 on page 14.

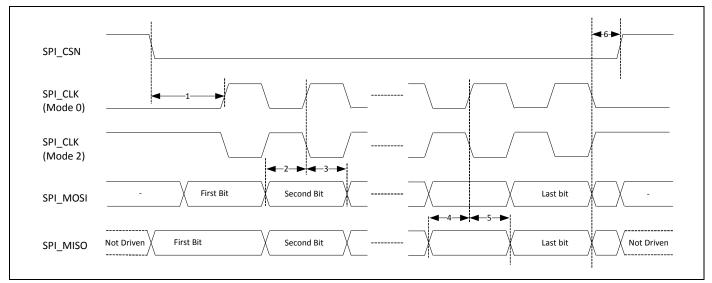


Figure 4. SPI Timing—Modes 0 and 2

Figure 5. SPI Timing—Modes 1 and 3

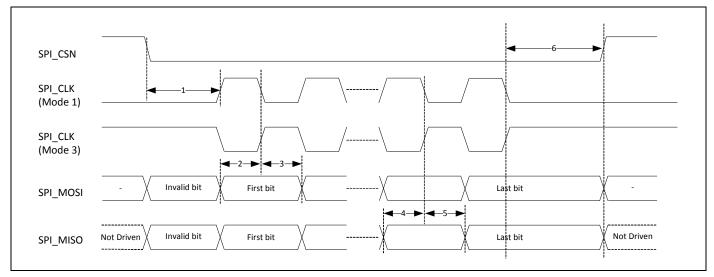




Table 10. SPI Interface Timing Specifications

Reference	Characteristics	Min.	Тур.	Max.
1	Time from CSN asserted to first clock edge	1 SCK	100	∞
2	Master setup time	-	1/2SCK	-
3	Master hold time	1/2SCK	-	-
4	Slave setup time	-	1/2 SCK	-
5	Slave hold time	1/2 SCK	_	-
6	Time from last clock edge to CSN deasserted	SCK	10 SCK	100

6.2 BSC Interface Timing

BSC interface timing is illustrated in Figure 6 and is defined in Table 11.



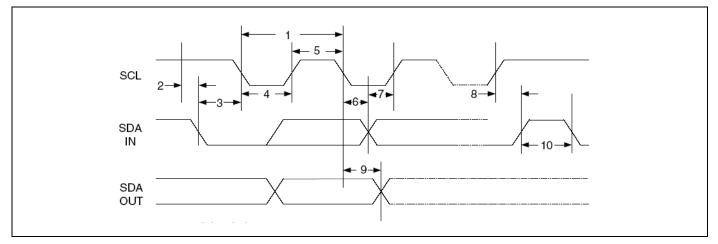


Table 11. BSC Interface Timing Specifications

Reference	Characteristics	Min.	Max.	Unit
1	Clock frequency	_	100, 400, 800, 1000	kHz
2	START condition setup time	650	-	ns
3	START condition hold time	280	-	ns
4	Clock low time	650	-	ns
5	Clock high time	280	-	ns
6	Data input hold time	0	-	ns
7	Data input setup time	100	-	ns
8	STOP condition setup time	280	-	ns
9	Output valid from clock	_	400	ns
10	Bus free time	650	_	ns



6.3 UART Timing

UART timing is illustrated in Figure 7 and defined in Table 12.

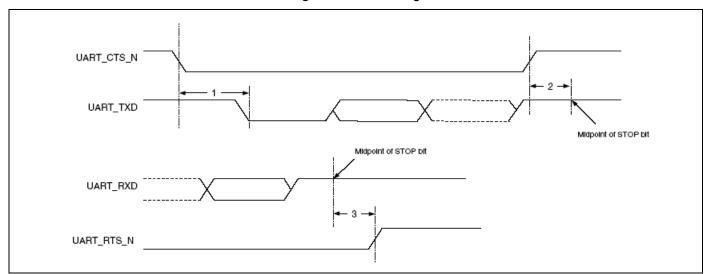


Table 12. UART Timing Specifications

Reference	Characteristics	Min.	Max.	Unit
1	Delay time, UART_CTS_N low to UART_TXD valid	-	24	Baudout cycles
2	Setup time, UART_CTS_N high before midpoint of stop bit	-	10	ns
3	Delay time, midpoint of stop bit to UART_RTS_N high	-	2	Baudout cycles



7. PCB Design and Manufacturing Recommendations

7.1 Pad and Solder Mask Opening Dimensions

CYW20737S pad and solder mask opening dimensions are defined in Table 13.

Table 13. Pad and Solder Mask Dimensions

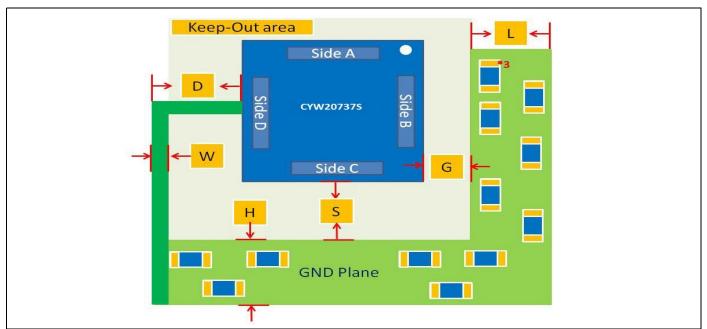
Pad Type	Pad Dimensions	Solder Mask Opening Dimensions	Unit
Туре А	0.6 × 0.25	0.7 × 0.35	
Туре В	0.55 × 0.3	0.65 × 0.4	mm
Туре С	0.4 × 0.4	0.5 × 0.5	

7.2 PCB Layout Recommendations

The following layout recommendations are referenced to Figure 8 on page 16.

- Connect to system ground from side D of the module (pins 13–22).
- The L-shaped ground plane is required for the embedded BLE antenna. Keep the GND continuous. Do not cut off the GND shape to accommodate trace routes.
- An L-shaped ground plane is required. If the L-shaped GND plane is located on the top layer of the PCB, do not place components on the ground plane. If this cannot be avoided, move the L-shaped ground plane to another layer.
- Antenna efficiency of 31–41% can be achieved based on the layout in Figure 8 on page 16 and the dimensions listed below. Following these layout recommendations is expected to yield 50+ meters of usable range; deviating from these recommendations may reduce the range of the antenna.
- □ D: 4.5 mm (typical)
- □ G, H, S: 3 mm (typical)
- □ L: 3 mm (minimum)
- □ W: 0.4 mm (typical)
- Route signal traces out of the module from side C (between pins 27 and 30) or side D (between pins 16 and 19) of the module. Traces can be overlapped to avoid routing through the keep-out area.
- Do not route traces from side A or side B.

Figure 8. PCB Layout Example





7.3 PCB Stencil

The recommended PCB stencil is shown in Figure 9 (all measurements in mm). Use an unsolder mask to set the module footprint.

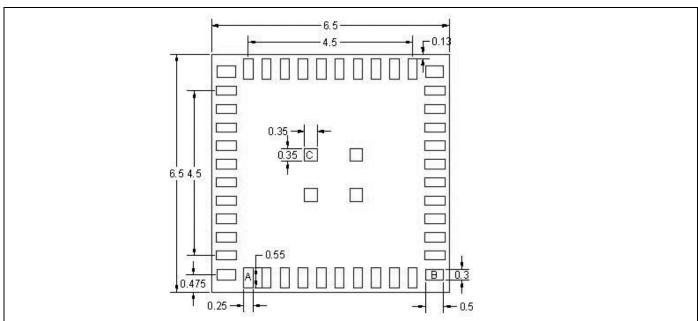
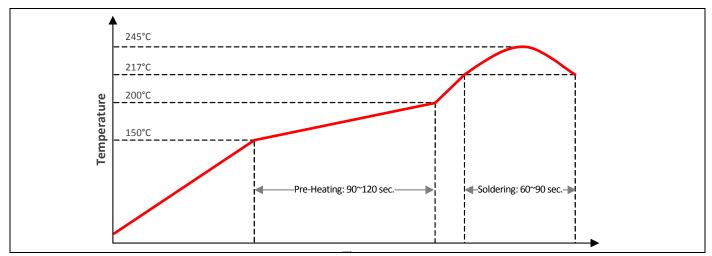


Figure 9. CYW20737S Stencil (Bottom View)

7.4 Solder Reflow

The recommended solder reflow profile for the CYW20737S is defined in Figure 10.

Figure 10. Solder Reflow Profile





8. Packaging and Storage Information

The CYW20737S is available in a tape and reel package and is shipped in an ESD-protected moisture-resistant (MSL-3) bag as shown in Figure 11. The storage temperature range is -40° C to $+125^{\circ}$ C.





The moisture sensitivity label on the CYW20737S shipping bag is shown in Figure 12 on page 19.





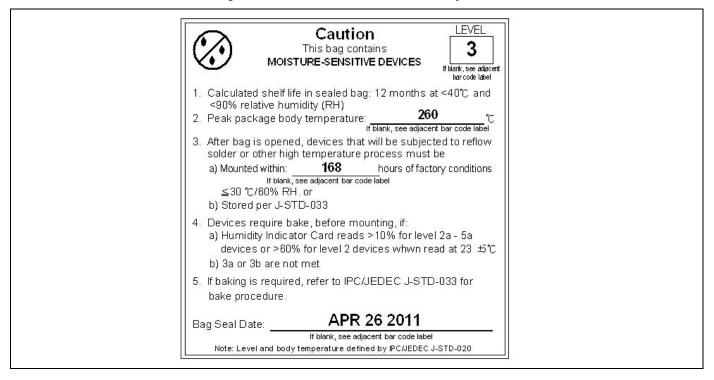
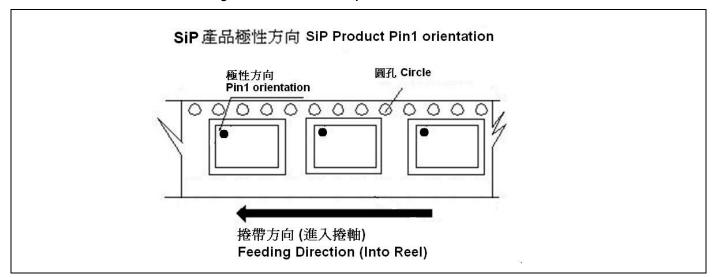


Figure 13 shows the location of pin 1 on the CYW20737S relative to its orientation on the tape packaging.

Figure 13. CYW20737S Tape and Reel Pin 1 Location

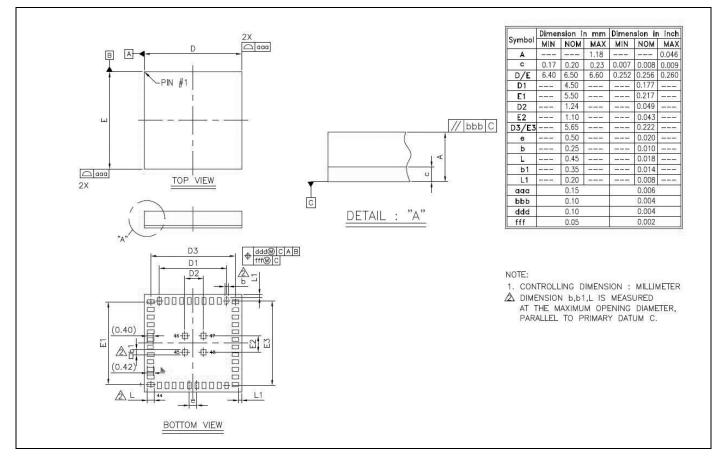




9. Mechanical Information

Package dimensions for the CYW20737S are shown in Figure 14.





Additional CYW20737S package dimensions are shown in Figure 15 on page 21.



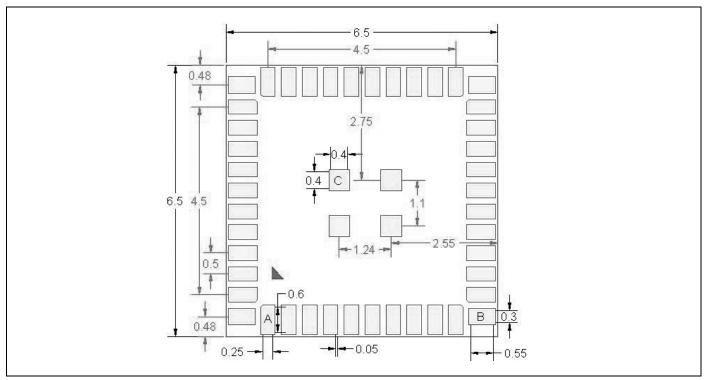


Figure 15. CYW20737S Pin Dimensions (Bottom View)



10. Ordering Information

Table 14. Ordering Information

Part Number	Package	Operating Temperature	Humidity
CYW20737S	48-pin LGA	–40°C to +85°C	95% max., noncondensing



Document History

Document Title: CYW20737S Bluetooth Low Energy System-in-Package (SiP) Module Document Number: 002-14888 Orig. of Submission Description of Change Revision ECN Orig. of Submission Description of Change

	Change	Date	ip
		00/26/2014	20737S-DS100-R:
_	_	09/20/2014	Initial release
			20737S-DS101-R:
-	UTSV	11/06/2015	Updated
			Table 5 on page 14
5444054	UTSV	09/23/2016	Updated to Cypress Template
5688156	AESATMP7	04/21/2017	Updated Cypress Logo and Copyright.
	5444054	Change - - - UTSV 5444054 UTSV	Change Date - - 09/26/2014 - UTSV 11/06/2015 5444054 UTSV 09/23/2016



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